

**Description**

The SX40H06DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 60V$   $I_D = 40A$

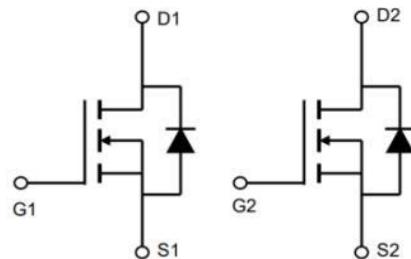
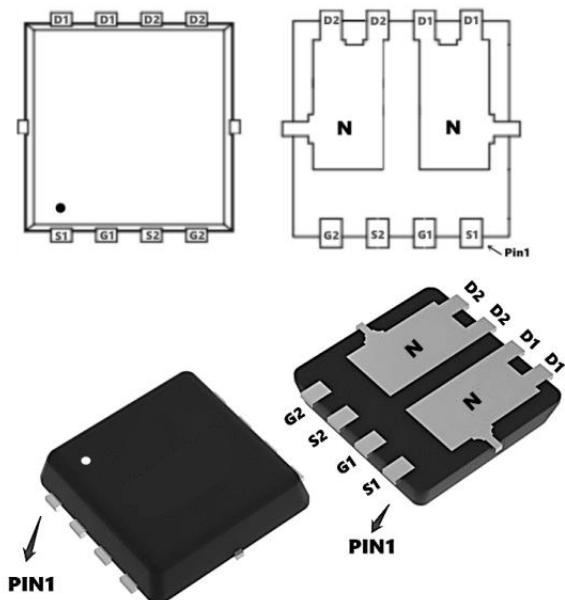
$R_{DS(ON)} < 32m\Omega$  @  $V_{GS}=10V$

**Application**

Battery protection

Load switch

Uninterruptible power supply

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	40	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	18	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	114	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	25.5	mJ
$I_{AS}$	Avalanche Current	22	A
$P_D@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	34.7	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	3.6	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	65	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.063	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=15\text{A}$	---	20	32	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	---	30	38	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.24	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=15\text{A}$	---	17	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3.2	---	$\Omega$
Q <sub>g</sub>	Total Gate Charge (4.5V)	$V_{DS}=48\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	12.6	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.2	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	6.3	---	
Td(on)	Turn-On Delay Time	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=10\text{A}$	---	8	---	ns
T <sub>r</sub>	Rise Time		---	14.2	---	
Td(off)	Turn-Off Delay Time		---	24.4	---	
T <sub>f</sub>	Fall Time		---	4.6	---	
C <sub>iss</sub>	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1378	---	pF
C <sub>oss</sub>	Output Capacitance		---	86	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	64	---	
I <sub>s</sub>	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	23	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	46	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $VDD=25\text{V}$ , $VGS=10\text{V}$ , $L=0.1\text{mH}$ , $IAS=22\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics

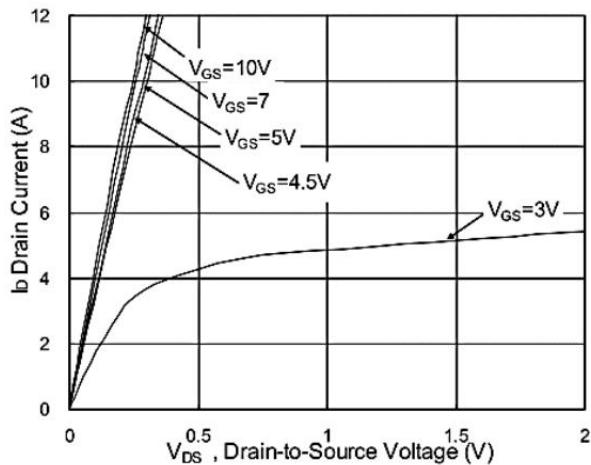


Fig.1 Typical Output Characteristics

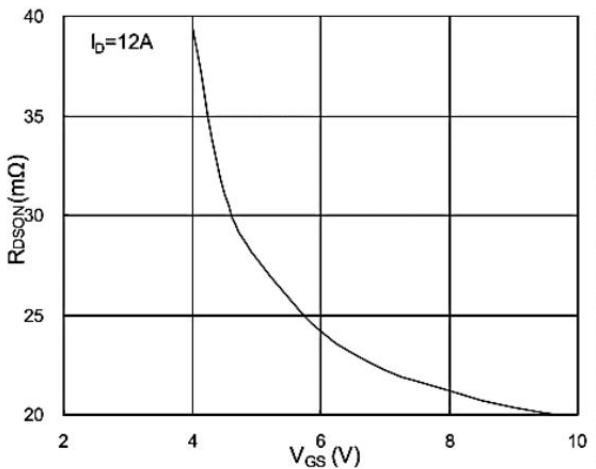


Fig.2 On-Resistance v.s Gate-Source

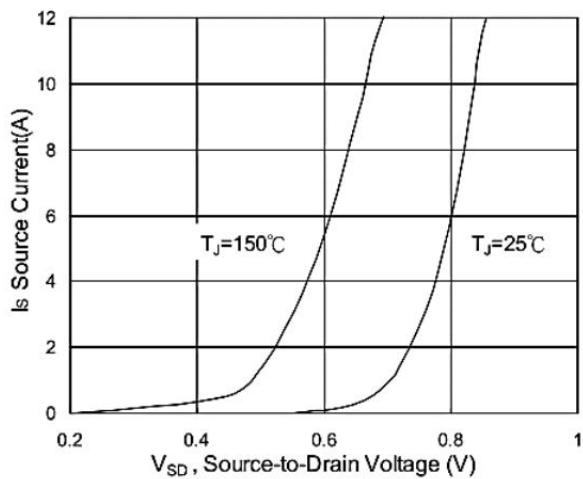


Fig.3 Forward Characteristics of Reverse

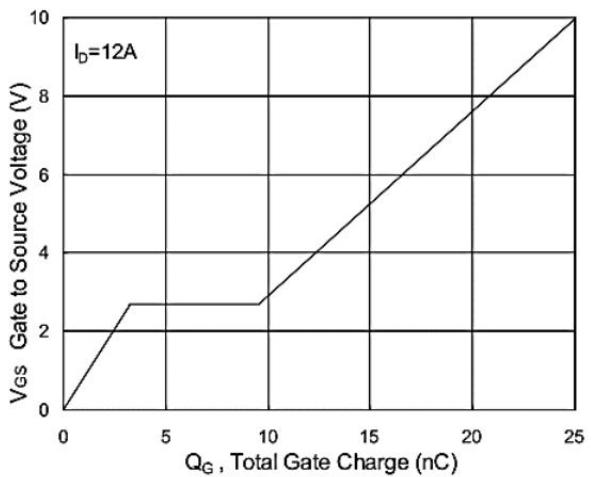


Fig.4 Gate-Charge Characteristics

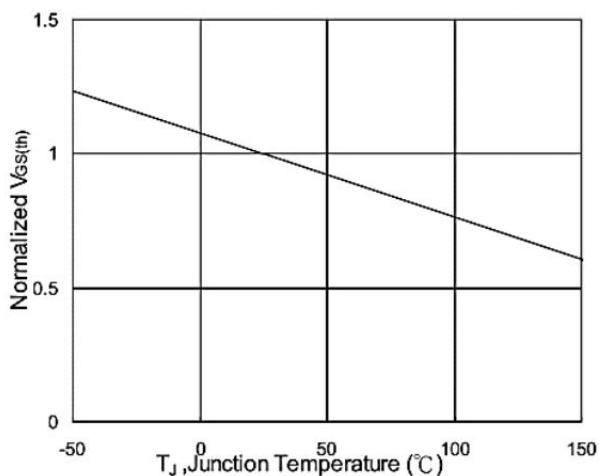


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

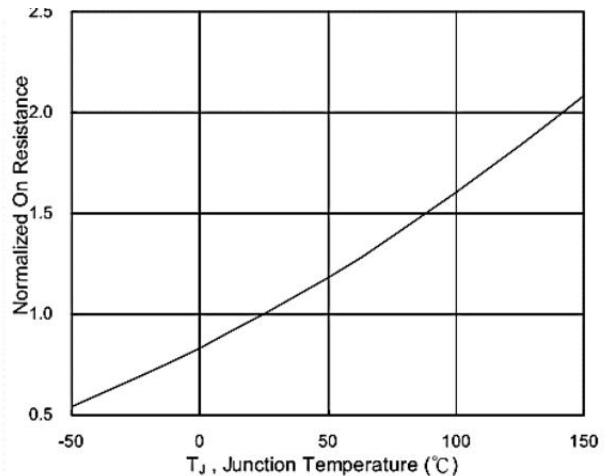


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

## Typical Characteristics

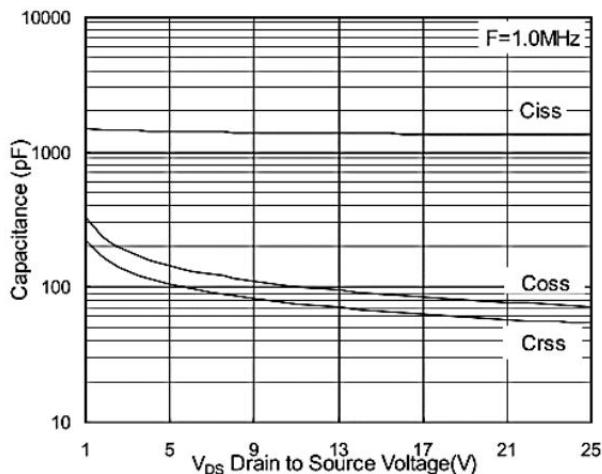


Fig.7 Capacitance

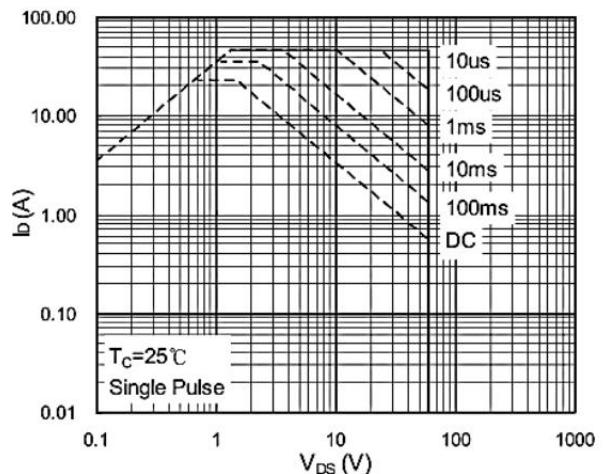


Fig.8 Safe Operating Area

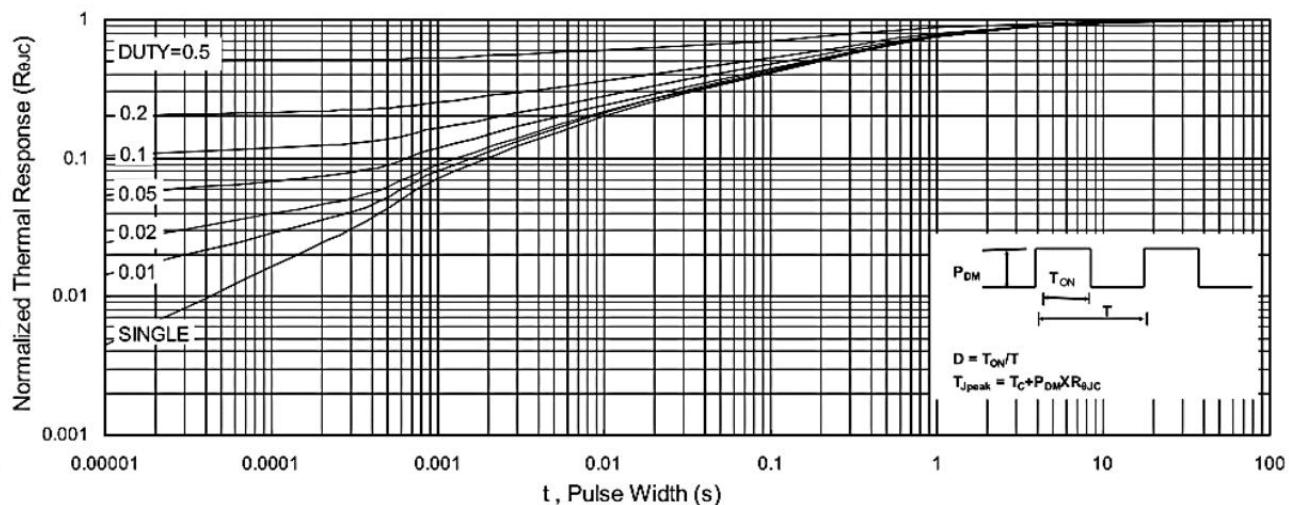


Fig.9 Normalized Maximum Transient Thermal Impedance

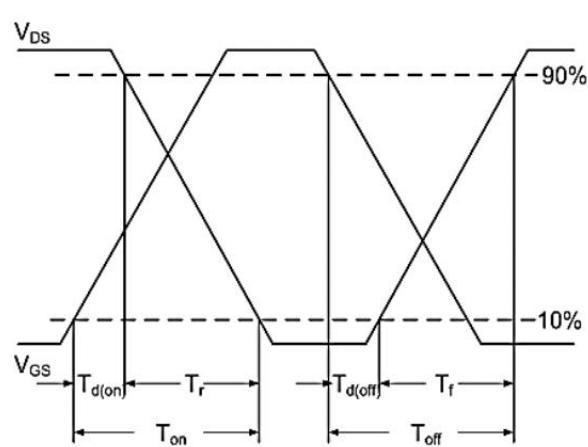


Fig.10 Switching Time Waveform

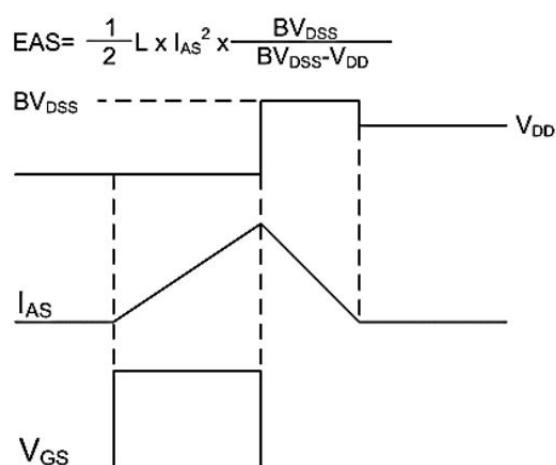
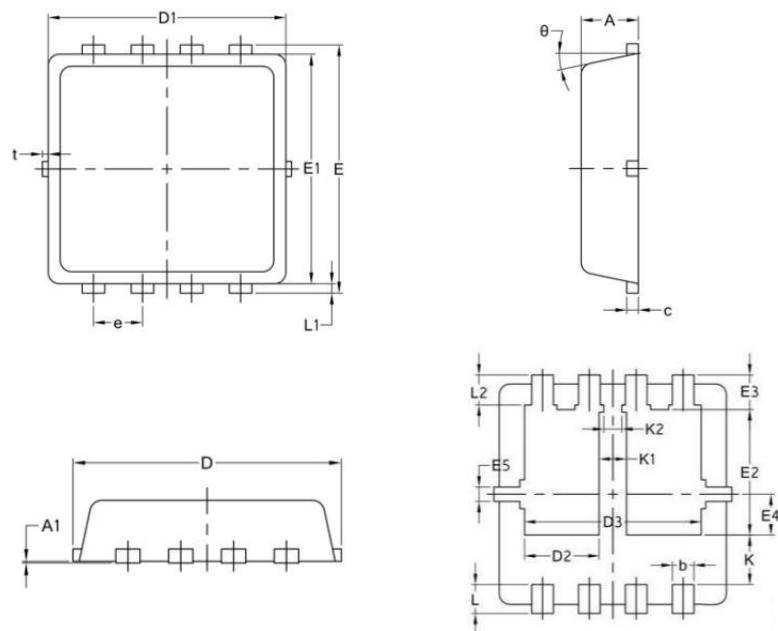


Fig.11 Unclamped Inductive Waveform

## Package Mechanical Data-PDFN3\*3-8L Double



Symbol	Common		
	Mm		
	Min	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.25	0.30	0.39
c	0.14	0.152	0.20
D	3.20	3.30	3.45
D1	3.05	3.15	3.25
D2	0.84	1.04	1.24
D3	2.30	2.45	2.60
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.60	1.74	1.90
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.50	0.69	0.80
K1	0.30	0.38	0.53
K2	0.15	0.25	0.35
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
L2	0.27	0.42	0.57
t	0	0.075	0.13
Φ	10°	12°	14°

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN3*3-8L		5000